

**PLATING PROCESSING METHOD OF GRIPPING SURFACE OF GRIPPING TOOL,
AND GRIPPING TOOL**

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A plating processing method of a gripping surface of a gripping tool includes: temporarily and evenly fixing a plurality of first diamond grains having a uniform first grain diameter so that tops of the first diamond grains can be aligned; adhering the first diamond grains by depositing a metal containing nickel on a gripping surface in a uniform thickness that does not exceed the first grain diameter after the first diamond grains have been temporarily fixed; placing a plurality of second diamond grains having a second grain diameter smaller than the first grain diameter on a metal surface of the gripping surface on which first diamond grains are not present and which is formed by depositing a metal containing nickel after the first diamond grains have been fixed; and adhering the second diamond grains by further depositing a metal containing nickel within a second plating solution on the metal surface in a uniform thickness that does not exceed the first diameter grain and the second diameter grain until a position relationship between the metal surface and the second diamond grains is not displaced even when the gripping tool is moved.

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Fig. 4B